			1)	
L Number	Hits	Search Text	DB	Time stamp
1	816192	bond\$3	USPAT;	2003/09/08 09:31
			US-PGPUB;	
			JPO	
2	202412	wafer\$1	USPAT;	2003/09/08 09:31
			US-PGPUB;	
			JPO	
3	280	thined or thining	USPAT;	2003/09/08 09:31
		_	US-PGPUB;	
			JPO	
4	311456	etch\$3	USPAT;	2003/09/08 09:31
			US-PGPUB;	
		•	JPO	
5	8467	bond\$3 near3 wafer\$1	USPAT;	2003/09/08 09:32
			US-PGPUB;	
1			ЛО	
6	34897	(thined or thining) or thinning	USPAT;	2003/09/08 09:33

((thined or thining) or thinning) and (bond\$3 near3 wafer\$1)

etch\$3 and (((thined or thining) or thinning) and (bond\$3 near3

(etch\$3 and (((thined or thining) or thinning) and (bond\$3 near3

(etch\$3 and (((thined or thining) or thinning) and (bond\$3 near3

(((thined or thining) or thinning) and (bond\$3 near3 wafer\$1)) not

((etch\$3 and (((thined or thining) or thinning) and (bond\$3 near3

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US-PGPUB; JPO

US-PGPUB; JPO 2003/09/08 09:33

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USPAT;

USPAT;

USPAT;

USPAT;

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USPAT;

JРО

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11

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933

840

829

237

696

462143

wafer\$1))

copper or cu

wafer\$1))) and "10"

wafer\$1))) and (copper or cu)

wafer\$1))) and (copper or cu))